

Title (en)

METHOD OF INVESTMENT CASTING CHAPLET

Title (de)

VERFAHREN FÜR FEINGUSSKERNSTÜTZE

Title (fr)

PROCÉDÉ DE CHAPELET DE COULÉE DE PRÉCISION

Publication

**EP 3693100 A1 20200812 (EN)**

Application

**EP 20150777 A 20200108**

Priority

GB 201901550 A 20190205

Abstract (en)

A method of supporting a soluble insert structure within a mould die ceramic injection moulding (CIM) process, the method comprising the steps of: forming at least one chaplet that supports the soluble insert structure within the die, the chaplet being formed of a ceramic material that has substantially similar physicochemical properties to the main internal core structure; and positioning the chaplet to contact the soluble insert structure to the die, the soluble insert being spaced away from an edge of the mould die. The chaplet may comprise a refractory material or a combination of refractory materials.

IPC 8 full level

**B22C 9/04** (2006.01); **B22C 9/10** (2006.01); **B22C 21/14** (2006.01); **B22D 17/24** (2006.01); **B28B 1/24** (2006.01); **B28B 7/34** (2006.01)

CPC (source: CN EP US)

**B22C 7/02** (2013.01 - US); **B22C 9/04** (2013.01 - EP); **B22C 9/10** (2013.01 - EP); **B22C 9/105** (2013.01 - CN); **B22C 9/108** (2013.01 - US); **B22C 9/24** (2013.01 - CN US); **B22C 21/14** (2013.01 - CN EP)

Citation (applicant)

- GB 2096523 B 19860409 - ROLLS ROYCE
- US 4384607 A 19830524 - WOOD ANDREW G B [GB], et al

Citation (search report)

- [A] US 2013186585 A1 20130725 - LEE CHING-PANG [US], et al
- [AD] US 4384607 A 19830524 - WOOD ANDREW G B [GB], et al
- [A] US 3659645 A 19720502 - ROSE JOHN A
- [A] EP 2777841 A1 20140917 - HOWMET CORP [US]
- [A] US 2012186768 A1 20120726 - SUN DONALD [US], et al

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**EP 3693100 A1 20200812**; CN 111515342 A 20200811; GB 201901550 D0 20190327; US 2020246861 A1 20200806

DOCDB simple family (application)

**EP 20150777 A 20200108**; CN 202010073093 A 20200121; GB 201901550 A 20190205; US 202016750641 A 20200123